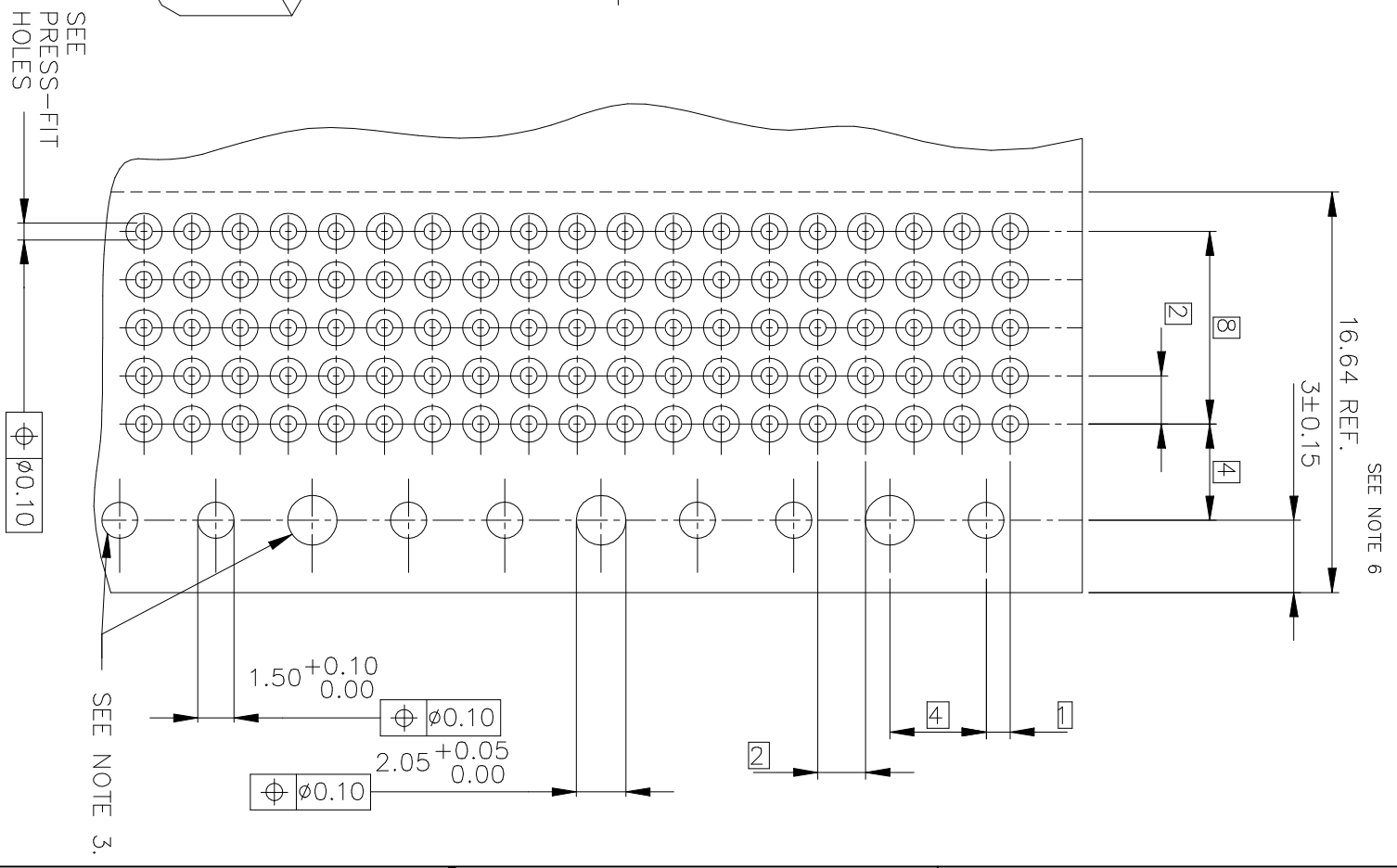
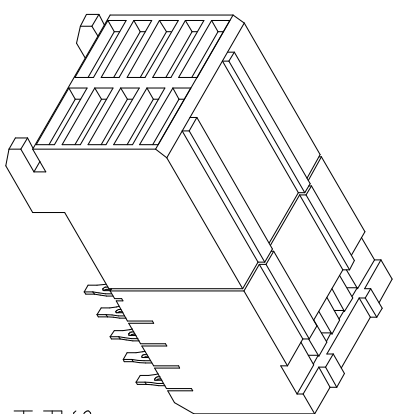
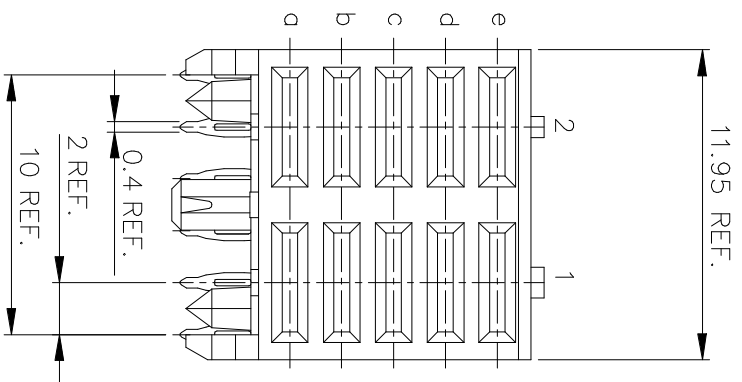
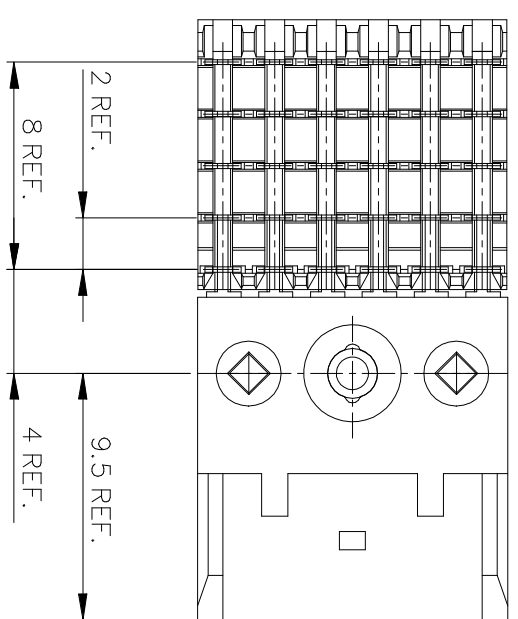
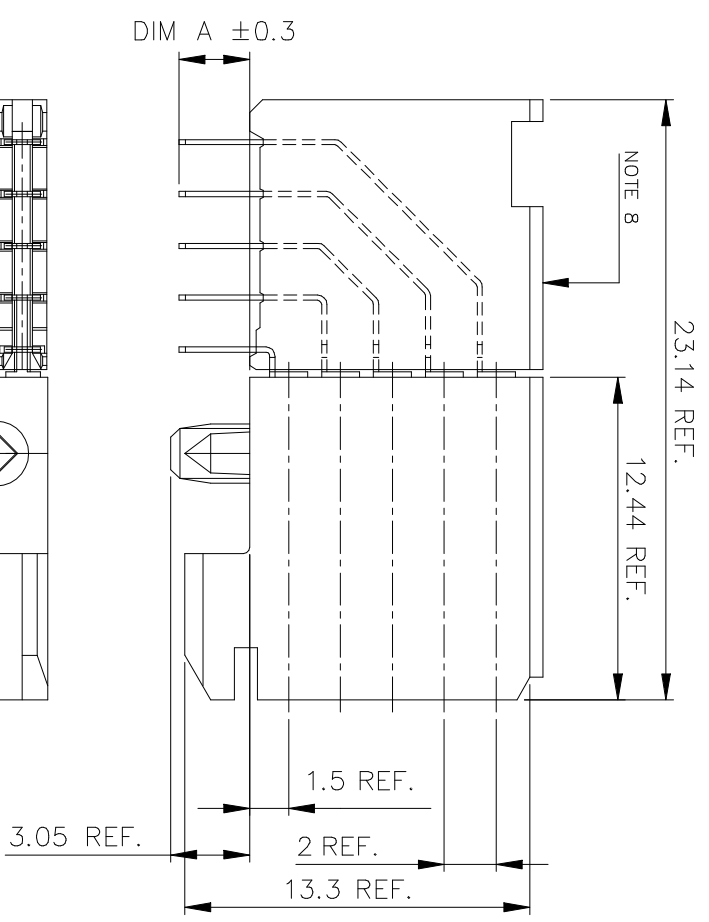


PC BOARD VERSIONS		
PRODUCT NR	PCB THICKNESS	DIM. A
89096-X02	1.6	2.90
89096-X12	2.4	3.53
89096-X02LF	1.6	2.90
89096-X12LF	2.4	3.53

PRESS-FIT HOLES	
HOLE DIAMETER AFTER PLATING	0.65-0.80
DRILLED HOLE	0.81-0.86
COPPER PLATING	0.025 MIN.
SnPb PLATING	0.005-0.015



RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

PLATING CONTACT AREA:

DASH NR:	PERFORMANCE LEVEL
-1YY	TELCORDIA CO
-2YY	CUSTOMER SPECIAL
-3YY	CUSTOMER SPECIAL
-9YY	TELCORDIA CO
-1YYLF	TELCORDIA CO
-2YYLF	CUSTOMER SPECIAL
-3YYLF	CUSTOMER SPECIAL
-9YYLF	TELCORDIA CO

- NOTES:
- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS FLAME RETARDANT ACC. UL 94-V0
 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - INDICATED HOLES ARE UNPLATED.
 - PLATING OF COMPLIANT SECTIONS 0.5-1.5 µm SnPb 85-97 IF THE PART NUMBER WAS ADDED A SUFFIX "LF", SO THE PLATING OF COMPLIANT SECTIONS 0.5-1.5 µm PURE Sn.
 - PRODUCT MARKING: PART NUMBER & BATCH ID.
 - SET BACK FOR PRESS BLOCK
 - SEE TA-941 FOR -XY2 APPLICATION TOOLING
 - TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
 - CURRENT RATING: 3 AMP PER PIN.
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECOND IN A WAVE SOLDER APPLICATION.
 - FOR THE PRODUCT WITH 30u" GOLD PLATING IN TERMINAL, THEY CAN BE REPLACED BY 30 GXT PLATING.

mat'l. code	surfactant	tolerance	projection	product family
ltr ecn no	dr date	ISO 1302	ISO 1101	METRAL (tm)
F D304-0066	CLU 04/201			
G D307-0458	Genh 11/15/07			
H D308-0171	TER 8/21/08			
J ELX-N-8176	NICK 8/26/15			
K ELX-N-26608	NZ 3/28/17			
	Chr E Feijen			
	oppd H v Woensel			
sheet index	revision sheet	k	1	



RA PF 12mm ASSEMBLY
sheet 1 of 1
89096
A3